

**In the Claim:**

1. (Currently Amended) A method of detecting a polishing end point in a chemical mechanical polishing process, comprising the steps of:

using a sensor ~~detecting to detect~~ a variation in the concentration of a material within an initial polishing layer or to ~~detect~~ a variation in the concentration of a material within a polishing stop layer, ~~which are by measuring the concentration of the material within the initial polishing layer or the concentration of the material within the polishing stop layer~~ contained in polishing wastewater drained during a polishing process;

using an ~~EDP~~pend point detection system to database information detected by the sensor;

feeding back ~~the a~~ result to a polisher in real time, wherein if ~~a result that there~~ is no change in the concentration of the material within the initial polishing layer is obtained, the result is the polishing process continuously proceeds with an initial polishing process condition;

if ~~a result that variation in~~ the concentration of the material within the initial polishing layer is reduced and ~~variation in~~ the concentration of the material within the polishing stop layer is increased, ~~is obtained, the result is~~ performing the polishing process ~~by lowering a~~ under a reduced polishing pressure; and

if ~~a result that variation in~~ the concentration of the material within the initial polishing layer is not reduced but kept constant and ~~variation in~~ the concentration of the material within the polishing stop layer is not increased but kept constant, ~~is obtained, the result is~~ using the ~~EDP~~pend point detection system to send a polishing process stop signal to the polisher, thus stopping the polishing process.